

AMENDMENTS TO THE CLAIMS

This listing of the claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. -20. (Cancelled)

21. (Currently Amended) A solder bump forming apparatus for forming a solder bump through heating and reflowing a solder composition on a substrate where a plurality of pad electrodes are provided, wherein[[:]] the solder composition is made of a mixture of solder particles and a liquid material that contains a flux component, which becomes liquid at a normal temperature or when heated,~~;~~and the solder bump forming apparatus comprising:

a heating device [[is]] provided for heating the solder composite from a first side of the substrate, wherein the heating device blows hot air, and wherein the blowing hot air of the heating device does not directly come in contact with the solder composition on the substrate within a space through which the substrate is conveyed; [[and]]

a thermostat device for controlling a temperature of the solder composition is provided at a position above a mount plate, which is located over a second side of the substrate, wherein the thermostat device includes a system in which a cool air or hot air of the thermostat device does not directly come in contact with the solder composition on the substrate within the space;

the thermostat device being enclosed within a thermostat enclosure and the heating device being enclosed within a heating device enclosure, the thermostat enclosure and heating

device enclosure preventing all blowing air of the solder bump forming apparatus from being blown within the space through which the substrate is conveyed, the thermostat enclosure including a thermostat circulation duct that defines at least part of a thermostat circulation path within the thermostat enclosure, and the heating device enclosure including a heating device circulation duct that defines at least part of a heating circulation path within the heating device enclosure;

the thermostat device having a thermostat blower, a main thermostat, a cool/heat storage member, a heat absorbing plate, and a sub-thermostat source;

the heating device having a heat blower, a main heating source, a heat storage member, an opening that is covered, and a sub-heating source; and

the thermostat blower circulates a thermostat medium along the thermostat circulation path, wherein the thermostat circulation path provides a thermostat flow path from the main thermostat source, through the cool/heat storage member, along the heat absorbing plate, through the thermostat circulation duct having the sub-thermostat source therein, to the thermostat blower, and returning to the main thermostat source, and the heat blower circulates hot air along the heating circulation path, wherein the heating circulation path provides a heating flow path from the main heating source, through the heat storage member, along the covered opening, through the heating device circulation duct having the sub-heating source therein, to the heat blower, and returning to the main heating source.

22. (Canceled)

23. (Previously Presented) The solder bump forming apparatus as claimed in claim 21, wherein the thermostat device comprises a radiation plate for heating the solder composition by radiant heat and a heating section for heating the radiation plate.

24. (Currently Amended) The solder bump forming apparatus as claimed in claim 21, wherein the ~~thermostat device comprises a heat absorbing plate for depriving~~ deprives heat of the solder composition, and ~~the thermostat device comprises an endothermic section for cooling the~~ heat absorbing plate.

25. (Original) The solder bump forming apparatus as claimed in claim 21, wherein the heating device applies heat by blowing hot air to a bottom side of the substrate.

26. (Original) The solder bump forming apparatus as claimed in claim 21, wherein the heating device heats a bottom side of the substrate by thermal conduction.

27. (Previously Presented) The solder bump forming apparatus as claimed in claim 21, wherein:

the substrate is immersed in the solder composition within a container; and  
the heating device heats the solder composition from the first side of the substrate through the container.

28-38 (Cancelled)